



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



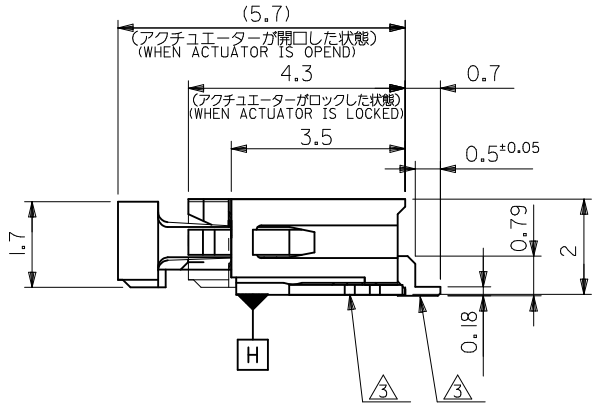
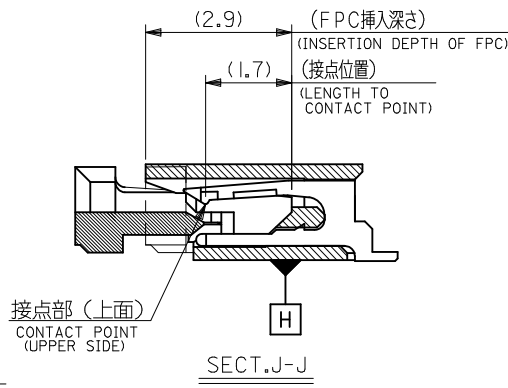
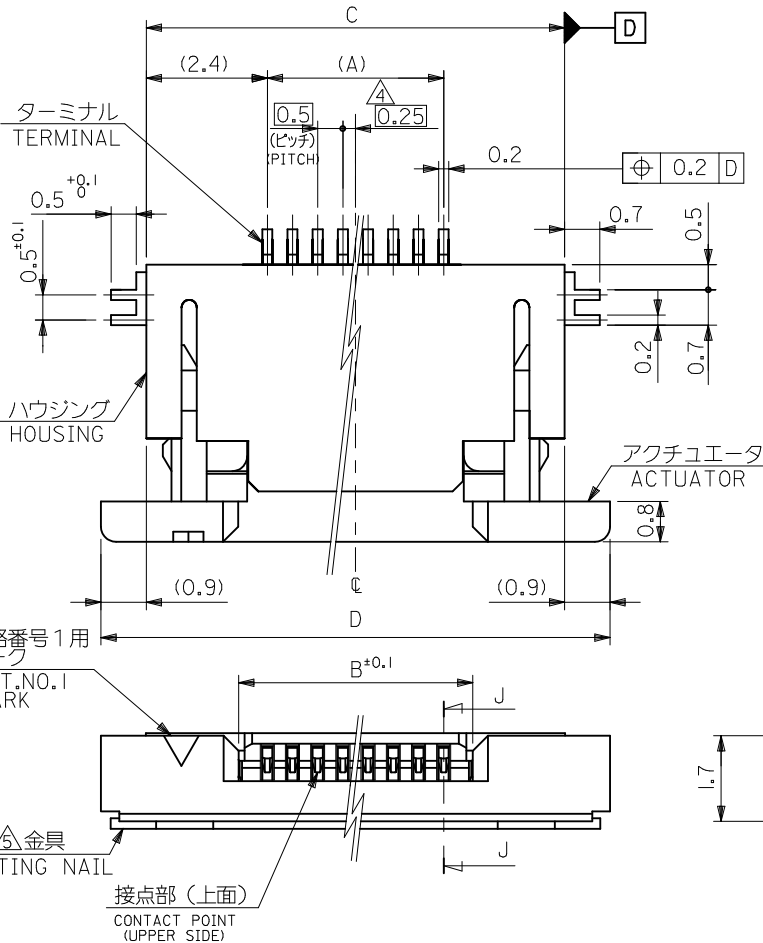
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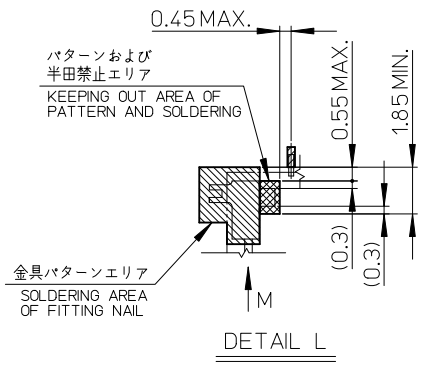
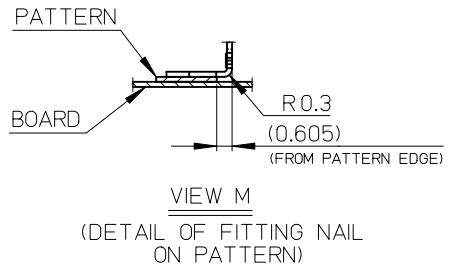
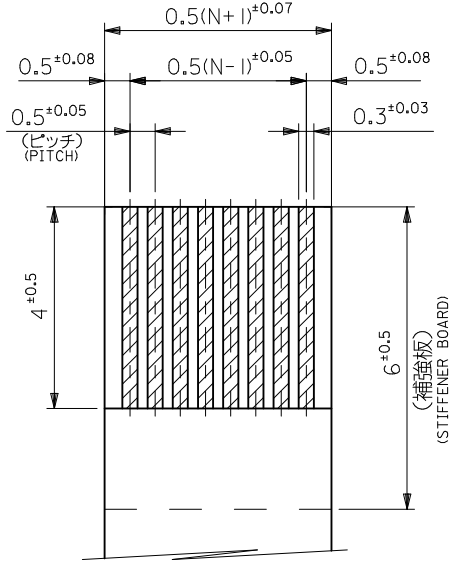
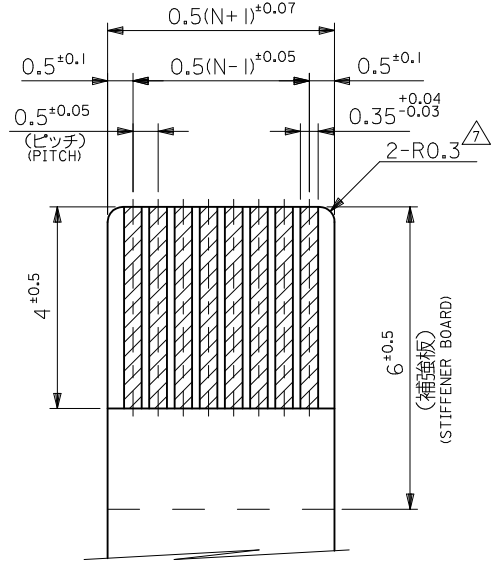
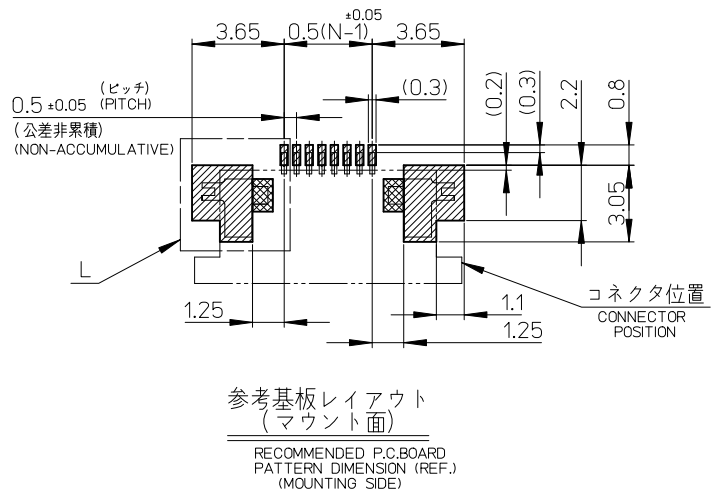
注記 NOTES

1. 使用材料 MATERIAL
- ハウジング HOUSING : ポリアミド46、ガラス充填、UL94V-0 (白) POLYAMIDE46, GLASS FILLED, UL94V-0(WHITE)
- アクチュエータ ACTUATOR : ポリフェニレンサルファイド ガラス充填、UL94V-0 (黒) POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0(BLACK)
- ターミナル TERMINAL : リン青銅、ニッケル下地鍍ピスマスメッキ (t=0.2) PHOSPOR BRONZE, TIN-BISMUTH OVER NICKEL PLATING
- 金具 FITTING NAIL : リン青銅、ニッケル下地純錫メッキ (t=0.2) PHOSPOR BRONZE, TIN OVER NICKEL PLATING
2. エンボステープ梱包時は、アクチュエータがロックした状態とする。
IN THE PACKAGE, ACTUATOR OF PART NO. 52745-**19 SHOULD BE LOCKED.
- △ ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 H に対し上方向 0.1 MAX.、下方向 0.15 MAX. とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM H UPPER DIRECTION: 0.1 MAX., LOWER DIRECTION: 0.15 MAX.
- △ 偶数極に適用。
APPLY FOR EVEN CIRCUIT.
- △ パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.
6. 本製品は 52745-**17 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 52745-**17
- △ RO.3は、FPCの導体部にかからないこと。
RO.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

16.1	14.3	10.65	9.5	52745-2096	52745-2019	20
15.6	13.8	10.15	9.0	-1996	-1919	19
15.1	13.3	9.65	8.5	-1896	-1819	18
14.6	12.8	9.15	8.0	-1796	-1719	17
14.1	12.3	8.65	7.5	-1696	-1619	16
13.6	11.8	8.15	7.0	-1596	-1519	15
13.1	11.3	7.65	6.5	-1496	-1419	14
12.6	10.8	7.15	6.0	-1396	-1319	13
12.1	10.3	6.65	5.5	-1296	-1219	12
11.6	9.8	6.15	5.0	-1196	-1119	11
11.1	9.3	5.65	4.5	-1096	-1019	10
10.6	8.8	5.15	4.0	-0996	-0919	9
10.1	8.3	4.65	3.5	-0896	-0819	8
9.6	7.8	4.15	3.0	-0796	-0719	7
9.1	7.3	3.65	2.5	-0696	-0619	6
8.1	6.3	2.65	1.5	52745-0496	52745-0419	4
D	C	B	(A)	EMBOSSED TAPE	MATERIAL NO.	極数
				ORDER No. オダー番		CIRCUIT

52745-**19 MODEL NO.

REVISED EC NO: J2011-0806 DRWN: JEBI SAWA 2010/12/13 CHKD: TAKAHASHI 2010/12/14 APPR: KMORIKAWA 2010/12/17	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			MM ONLY	---	METRIC	
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE	0.5 FPC CONN ASSY ZIF UPR CONT -LEAD FREE- MOLEX INCORPORATED
	10 OVER 30 UNDER	±0.25	T. UENO	'04/01/28		
30 OVER	±0.3	CHECKED BY	DATE			
		M. SASAO	'04/01/28			
		APPROVED BY	DATE			
		M. SASAO	'04/01/28			
		ANGULAR	±3 °	MATERIAL NO.	DOCUMENT NO.	SHEET NO.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE	SD-52745-048	1 OF 2
		SIZE	A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



適合FPC推奨寸法
 APPLICABLE FPC
 RECOMMENDED DIMENSION
 (仕上がり厚さ: 0.3±0.03)
 (THICKNESS: 0.3±0.03)

適合FFC推奨寸法
 APPLICABLE FFC
 RECOMMENDED DIMENSION
 (仕上がり厚さ: 0.3±0.03)
 (THICKNESS: 0.3±0.03)

FPCについて:
 打抜き方向は導体側から補強板側を推奨致します。
 補強フィルム材質はポリイミドを推奨致します。
 接着剤は熱硬化接着剤を推奨致します。

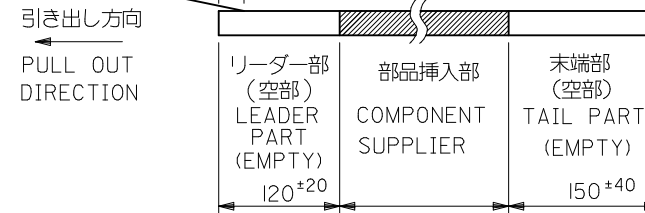
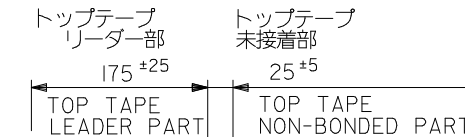
ABOUT FPC:
 RECOMMENDED PUNCHER DIRECTION: FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
 RECOMMENDED MATERIAL: STIFFENER FILM: POLYIMIDE
 BONDING AGENT: THERMOSETTING BONDING AGENT

52745-**-19 MODEL NO.

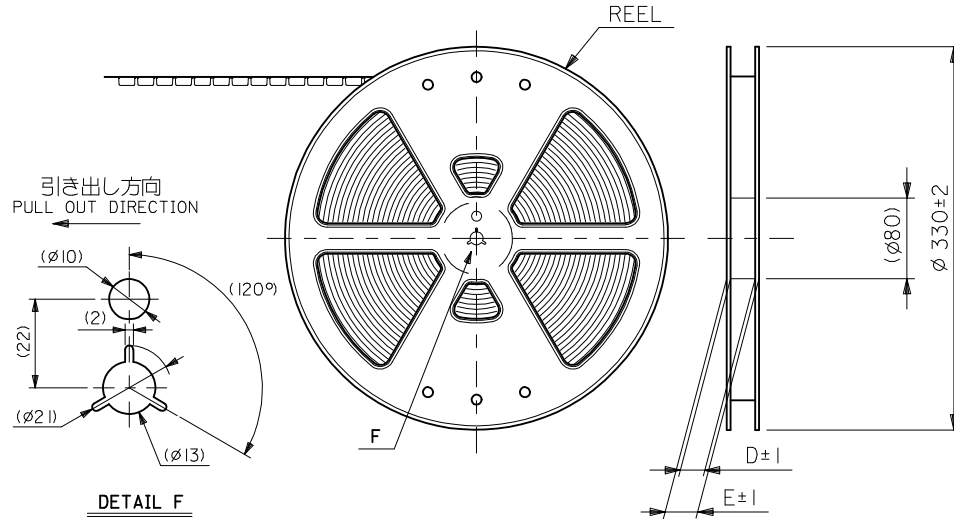
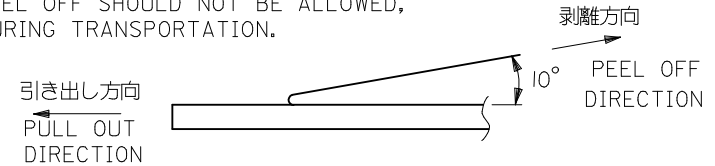
REVISED EC NO: J2011-0806 DRWN: JEBI SAWA 2010/12/13 CHKD: TAKAHASHI 2010/12/14 APPR: KMORI KAWA 2010/12/17	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY T. UENO	DATE '04/01/28	TITLE 0.5 FPC CONN ASSY ZIF UPR CONT -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE '04/01/28	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE '04/01/28			
	ANGULAR ±3 °		MATERIAL NO. SEE SHEET 1		DOCUMENT NO. SD-52745-048	SHEET NO. 2 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

注記 NOTES

- 製品番号 52745-**-19 の梱包状態はアクチュエータがロックした状態とする。
詳細寸法については図面 SD-52745-048 を参照下さい。
IN THE PACKAGE,ACTUATOR OF PART NO.52745-**-19 SHOULD BE LOCKED
RE DETAILED DIMENSIONS,SEE SD-52745-048.
- 梱包数量：1000個/リール
NUMBER OF CONNECTORS:1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- トップテープの剥離強度：(剥離方向は下図参照)
0.1N~1.3N(10gf~130gf) 尚、本規格値は、出荷時に適用。
(但し、輸送時に剥離が発生しない事。)
PEELING OFF FORCE OF TOP TAPE:
0.1N~1.3N(10gf~130gf)(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
PEEL OFF SHOULD NOT BE ALLOWED,
DURING TRANSPORTATION.



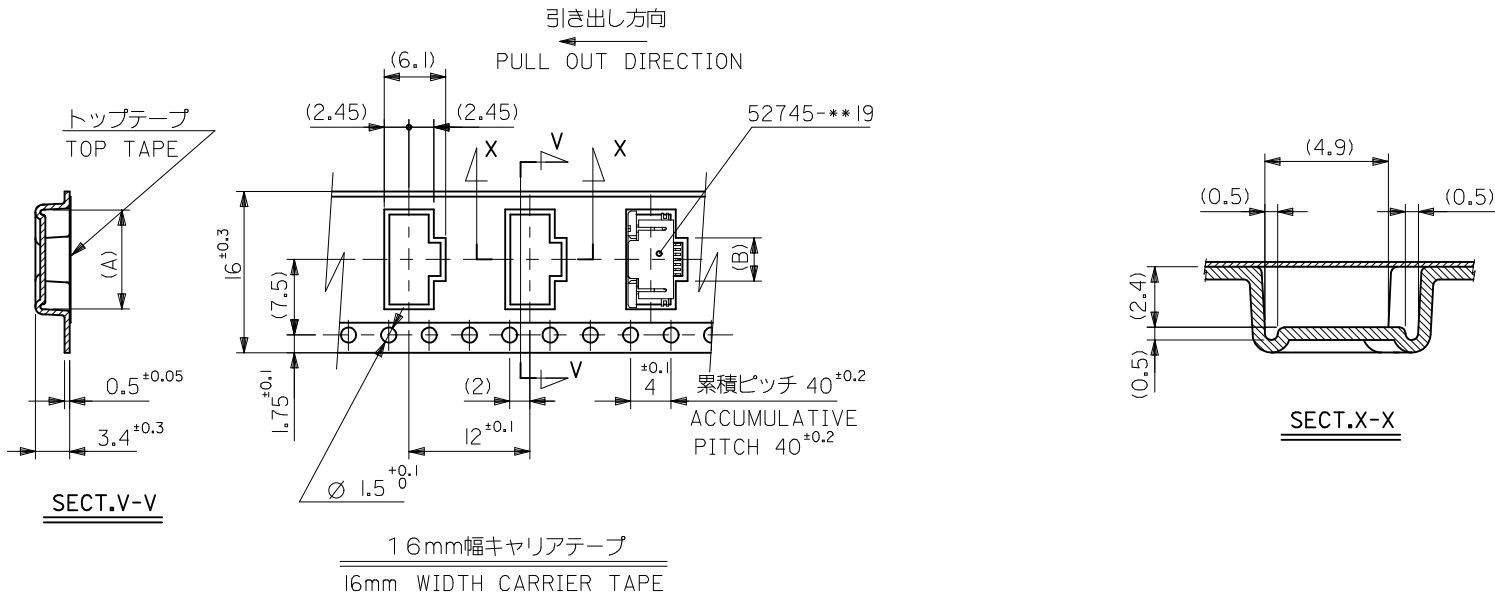
- 材料 キャリアテープ：ポリプロピレン (PP)
トップテープ：PET, PE, PEF
リール：ポリスチレン (PS) <リサイクル材を含む>
MATERIAL CARRIER TAPE:POLYPROPYLENE
TOP TAPE:PET,PE,PEF
REEL:POLYSTYRENE(PS)
<RECYCLE MATERIAL CONTAINED>

- 本製品は 52745-**-90 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 52745-**-90

- 本製品は乾燥剤入り、ハイバリア梱包仕様である。
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

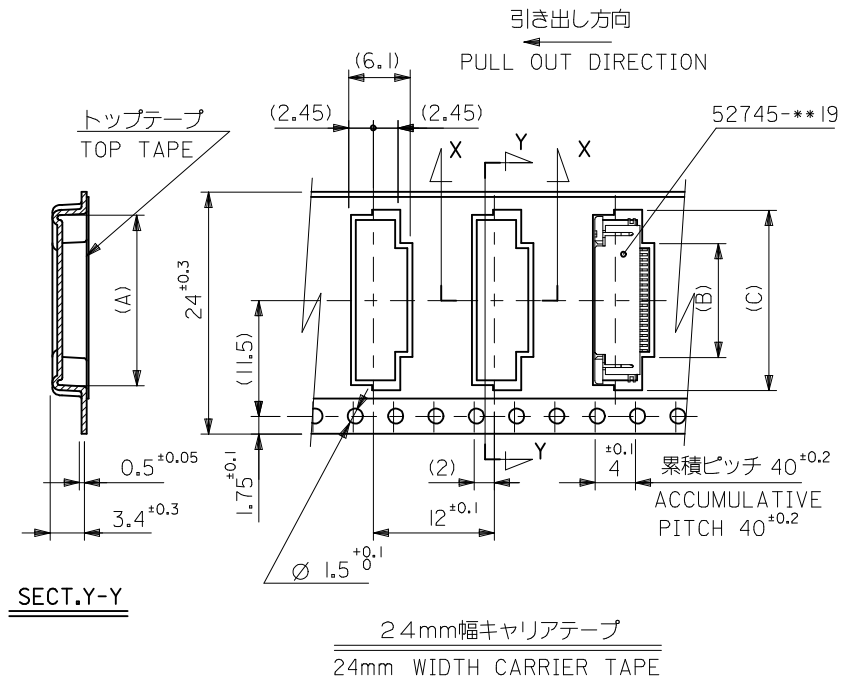
52745-**-96 MODEL NO.

REVISED EC NO.: J2009-2061 DRWN:TKON 2009/05/20 CHKD:HMATSUMOTO 2009/05/21 APPR:NIKIITA 2009/05/21	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY T.UENO	DATE 2004/01/08	TITLE 0.5 FPC CONN UPR CONT EMBSTP PKG -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY M.SASAO	DATE 2004/01/08	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY M.SASAO	DATE 2004/01/08	MATERIAL NO. SEE SHEET 2,3	DOCUMENT NO. SD-52745-049	SHEET NO. 1 OF 3
REV	ANGULAR ±3° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

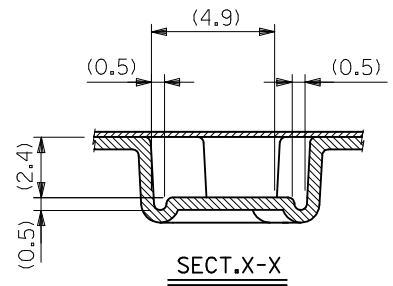


16	21.4	17.4	17.5	2.8	8.4	52745-0496	4
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MATERIAL NO.	極数 CIRCUIT

REVISED EC NO.: J2009-2061 DRWN:TKON 2009/05/20 CHKD:HMATSUMOTO 2009/05/21 APPR:NUKITA 2009/05/21	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE		
	10 OVER 30 UNDER	±0.25	T. UENO	2004/01/08	0.5 FPC CONN UPR CONT EMBSTP PKG -LEAD FREE-		
	30 OVER	±0.3	CHECKED BY	DATE	MOLEX INCORPORATED		
ANGULAR	±3°	APPROVED BY	DATE	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-52745-049		2 OF 3	
		SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



SECT.Y-Y



24	29.4	25.4	17.4	10.8	16.4	52745-2096	20
			16.9	10.3	15.9	-1996	19
			16.4	9.8	15.4	-1896	18
			15.9	9.3	14.9	-1796	17
			15.4	8.8	14.4	-1696	16
			14.9	8.3	13.9	-1596	15
			14.4	7.8	13.4	-1496	14
			13.9	7.3	12.9	-1396	13
			13.4	6.8	12.4	-1296	12
			12.9	6.3	11.9	-1196	11
			12.4	5.8	11.4	-1096	10
			11.9	5.3	10.9	-0996	9
			11.4	4.8	10.4	-0896	8
10.9	4.3	9.9	-0796	7			
10.4	3.8	9.4	52745-0696	6			
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MATERIAL NO.	極数 CIRCUIT

REVISED EC NO: J2009-2061 DRWN:TKON 2009/05/20 CHKD:HMATSUMOTO 2009/05/21 APPR:NUKITA 2009/05/21	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY T.UENO	DATE 2004/01/08	TITLE 0.5 FPC CONN UPR CONT EMBSTP PKG -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY M.SASAO	DATE 2004/01/08	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY M.SASAO	DATE 2004/01/08	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-52745-049	SHEET NO. 3 OF 3
	ANGULAR ±3°		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
REV	DESCRIPTION	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					